



**THE DATASHEET OF
MJD253-001**



MJD243 (NPN), MJD253 (PNP)

Complementary Silicon Plastic Power Transistors

DPAK-3 for Surface Mount Applications

Designed for low voltage, low-power, high-gain audio amplifier applications.

Features

- High DC Current Gain
- Lead Formed for Surface Mount Applications in Plastic Sleeves (No Suffix)
- Straight Lead Version in Plastic Sleeves (“-1” Suffix)
- Low Collector-Emitter Saturation Voltage
- High Current-Gain – Bandwidth Product
- Annular Construction for Low Leakage
- Epoxy Meets UL 94 V-0 @ 0.125 in
- NJV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

MAXIMUM RATINGS

| Rating | Symbol | Value | Unit |
|--|----------------|--------------|--------------------------|
| Collector-Base Voltage | V_{CB} | 100 | Vdc |
| Collector-Emitter Voltage | V_{CEO} | 100 | Vdc |
| Emitter-Base Voltage | V_{EB} | 7.0 | Vdc |
| Collector Current – Continuous | I_C | 4.0 | Adc |
| Collector Current – Peak | I_{CM} | 8.0 | Adc |
| Base Current | I_B | 1.0 | Adc |
| Total Device Dissipation @ $T_C = 25^\circ\text{C}$ Derate above 25°C | P_D | 12.5 0.1 | W W/ $^\circ\text{C}$ |
| Total Device Dissipation @ $T_A = 25^\circ\text{C}$ (Note 2) Derate above 25°C | P_D | 1.4 0.011 | W W/ $^\circ\text{C}$ |
| Operating and Storage Junction Temperature Range | T_J, T_{stg} | -65 to +150 | $^\circ\text{C}$ |
| ESD – Human Body Model | HBM | 3B | V |
| ESD – Machine Model | MM | C | V |

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. When surface mounted on minimum pad sizes recommended.

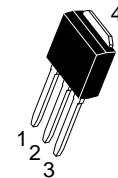
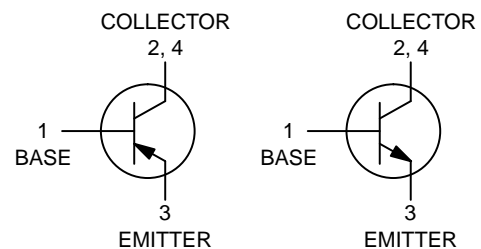


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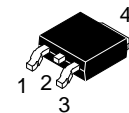
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4.0 A, 100 V, 12.5 W POWER TRANSISTOR

COMPLEMENTARY

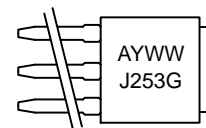


IPAK
CASE 369D
STYLE 1

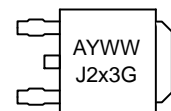


DPAK-3
CASE 369C
STYLE 1

MARKING DIAGRAMS



IPAK



DPAK

- A = Assembly Location
- Y = Year
- WW = Work Week
- x = 4 or 5
- G = Pb-Free Package

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 6 of this data sheet.

MJD243 (NPN), MJD253 (PNP)

THERMAL CHARACTERISTICS

| Characteristic | Symbol | Value | Unit |
|--|-----------------|-------|---------------|
| Thermal Resistance Junction-to-Case | $R_{\theta JC}$ | 10 | $^{\circ}C/W$ |
| Junction-to-Ambient (Note 2) | $R_{\theta JA}$ | 89.3 | |

2. When surface mounted on minimum pad sizes recommended.

ELECTRICAL CHARACTERISTICS ($T_C = 25^{\circ}C$ unless otherwise noted)

| Characteristic | Symbol | Min | Max | Unit |
|----------------|--------|-----|-----|------|
|----------------|--------|-----|-----|------|

OFF CHARACTERISTICS

| | | | | |
|---|---------------|----------|------------|-------------------|
| Collector-Emitter Sustaining Voltage (Note 3) ($I_C = 10$ mAdc, $I_B = 0$) | $V_{CE(sus)}$ | 100 | - | Vdc |
| Collector Cutoff Current ($V_{CB} = 100$ Vdc, $I_E = 0$) ($V_{CB} = 100$ Vdc, $I_E = 0$, $T_J = 125^{\circ}C$) | I_{CBO} | - | 100 | nAdc μ Adc |
| Emitter Cutoff Current ($V_{BE} = 7.0$ Vdc, $I_C = 0$) | I_{EBO} | - | 100 | nAdc |
| DC Current Gain (Note 3) ($I_C = 200$ mAdc, $V_{CE} = 1.0$ Vdc) ($I_C = 1.0$ Adc, $V_{CE} = 1.0$ Vdc) | h_{FE} | 40 15 | 180 - | - |
| Collector-Emitter Saturation Voltage (Note 3) ($I_C = 500$ mAdc, $I_B = 50$ mAdc) ($I_C = 1.0$ Adc, $I_B = 100$ mAdc) | $V_{CE(sat)}$ | - - | 0.3 0.6 | Vdc |
| Base-Emitter Saturation Voltage (Note 3) ($I_C = 2.0$ Adc, $I_B = 200$ mAdc) | $V_{BE(sat)}$ | - | 1.8 | Vdc |
| Base-Emitter On Voltage (Note 3) ($I_C = 500$ mAdc, $V_{CE} = 1.0$ Vdc) | $V_{BE(on)}$ | - | 1.5 | Vdc |

DYNAMIC CHARACTERISTICS

| | | | | |
|--|----------|----|----|-----|
| Current-Gain - Bandwidth Product (Note 4) ($I_C = 100$ mAdc, $V_{CE} = 10$ Vdc, $f_{test} = 10$ MHz) | f_T | 40 | - | MHz |
| Output Capacitance ($V_{CB} = 10$ Vdc, $I_E = 0$, $f = 0.1$ MHz) | C_{ob} | - | 50 | pF |

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

3. Pulse Test: Pulse Width = 300 μ s, Duty Cycle \approx 2%.

4. $f_T = |h_{FE}| \cdot f_{test}$.

MJD243 (NPN), MJD253 (PNP)

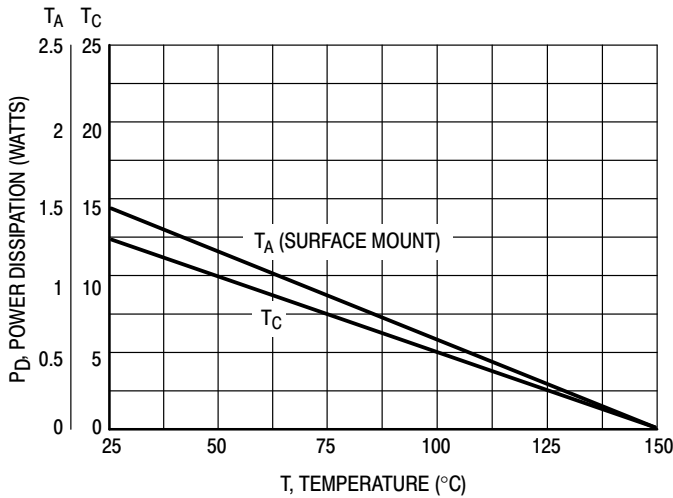


Figure 1. Power Derating

There are two limitations on the power handling ability of a transistor: average junction temperature and second breakdown. Safe operating area curves indicate $I_C - V_{CE}$ limits of the transistor that must be observed for reliable operation; i.e., the transistor must not be subjected to greater dissipation than the curves indicate.

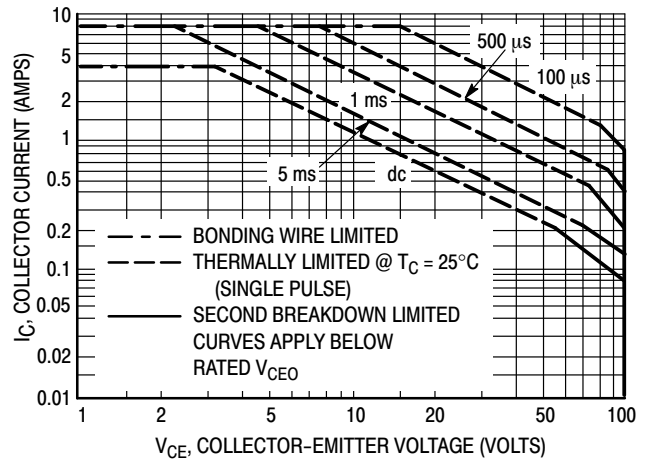


Figure 2. Active Region Maximum Safe Operating Area

The data of Figure 2 is based on $T_{J(pk)} = 150^\circ\text{C}$; T_C is variable depending on conditions. Second breakdown pulse limits are valid for duty cycles to 10% provided $T_{J(pk)} \leq 150^\circ\text{C}$. $T_{J(pk)}$ may be calculated from the data in Figure 3. At high case temperatures, thermal limitations will reduce the power that can be handled to values less than the limitations imposed by second breakdown.

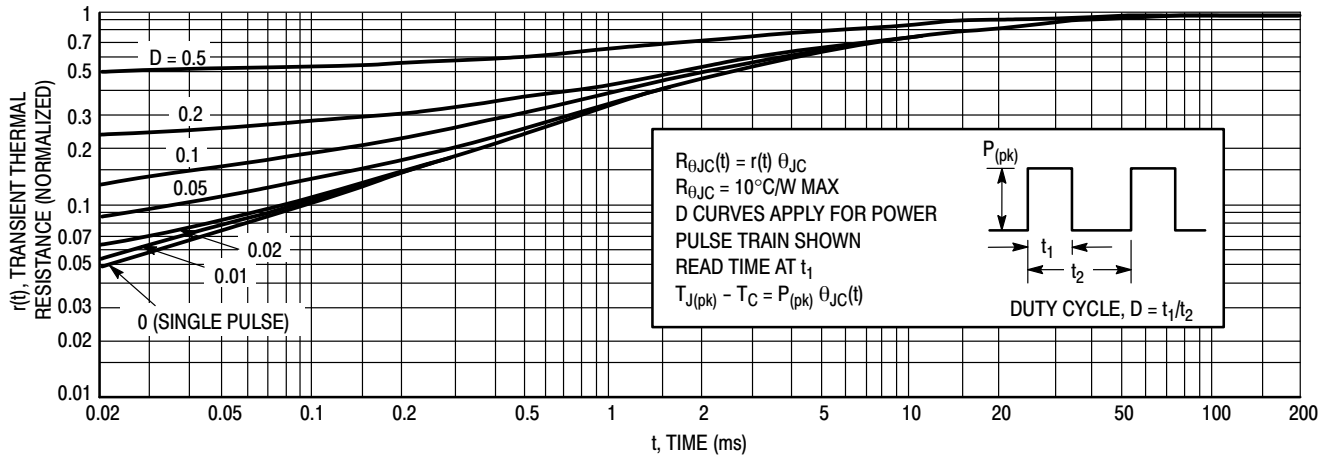
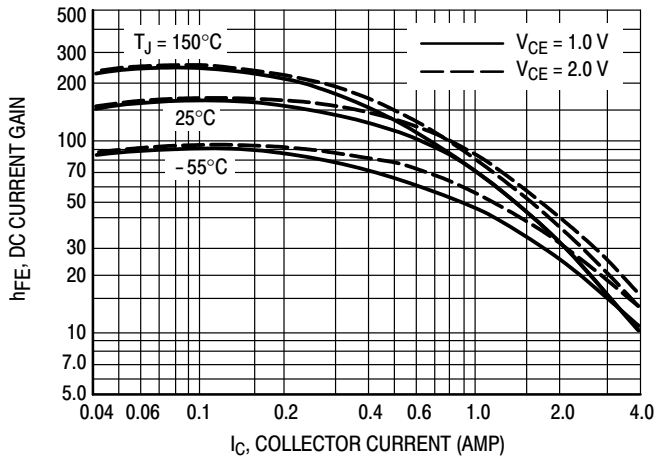


Figure 3. Thermal Response

MJD243 (NPN), MJD253 (PNP)

**NPN
MJD243**



**PNP
MJD253**

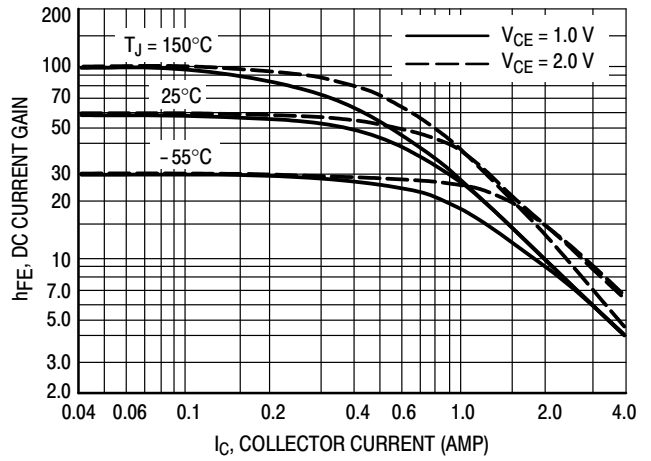


Figure 4. DC Current Gain

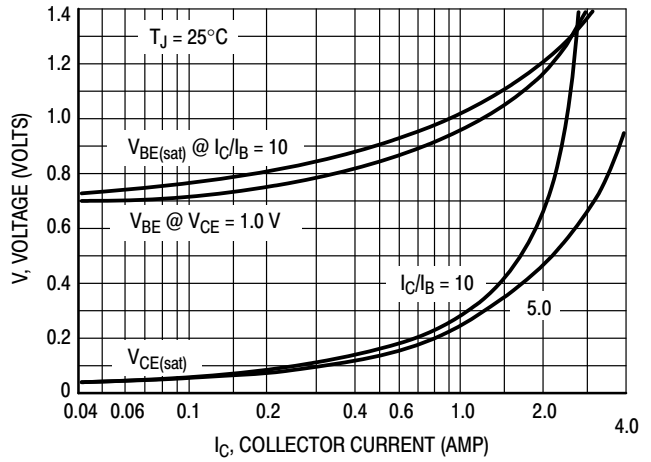
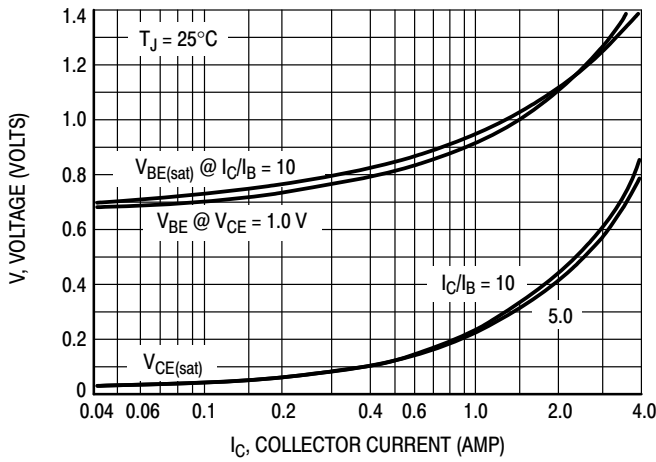


Figure 5. "On" Voltages

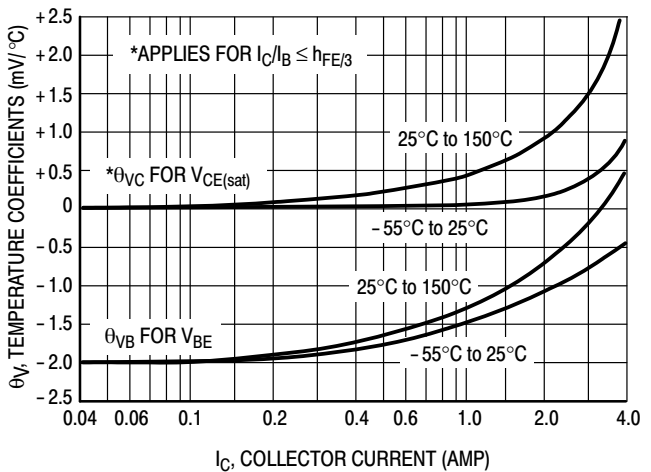
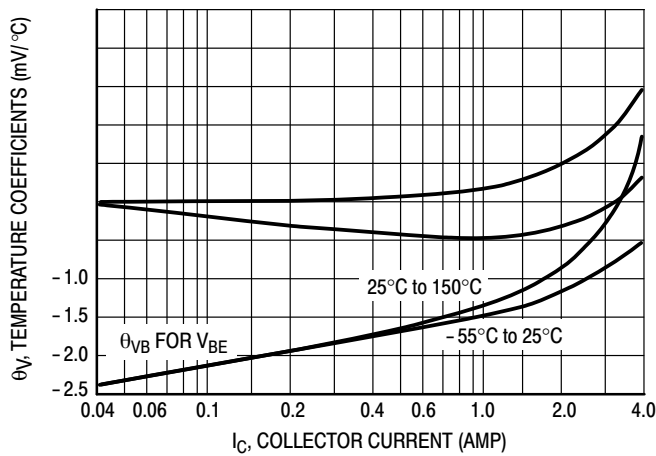


Figure 6. Temperature Coefficients

MJD243 (NPN), MJD253 (PNP)

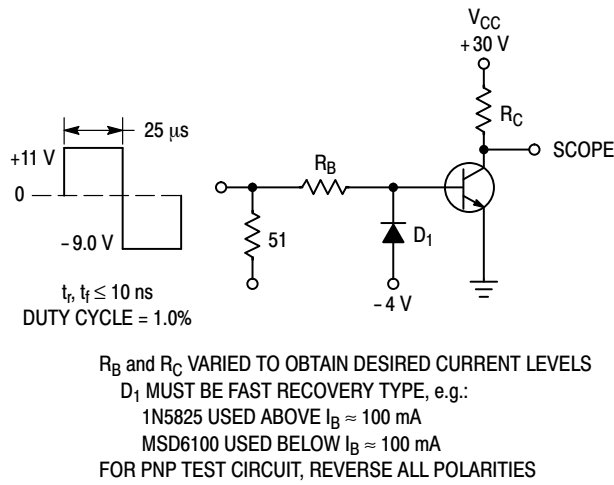


Figure 7. Switching Time Test Circuit

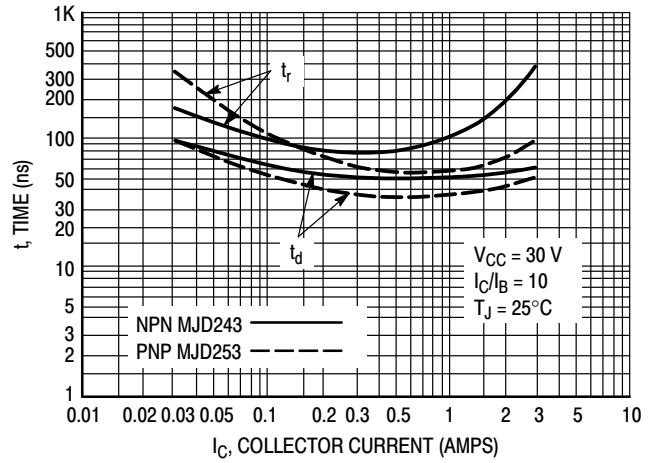


Figure 8. Turn-On Time

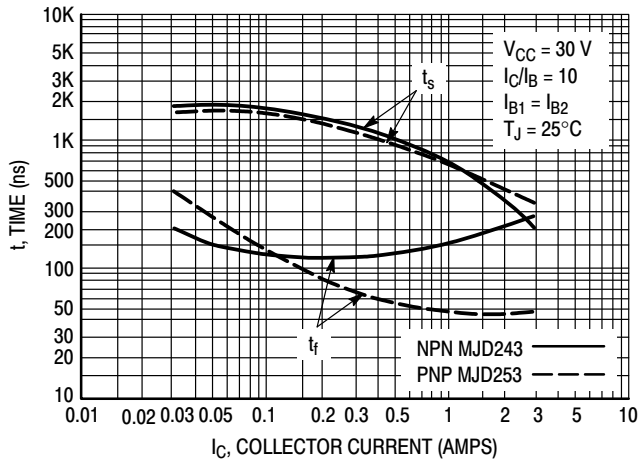


Figure 9. Turn-Off Time

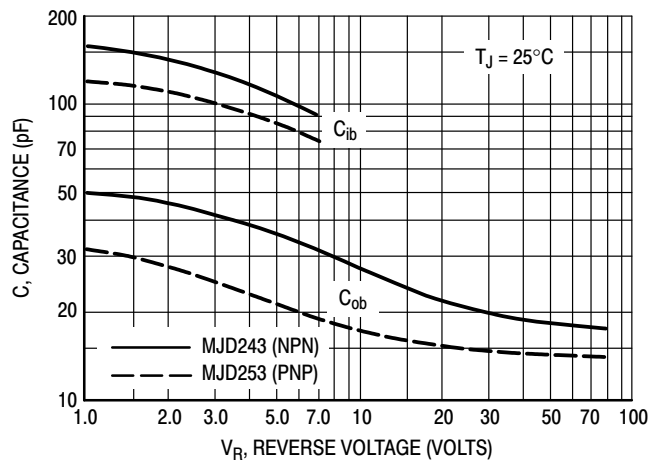


Figure 10. Capacitance

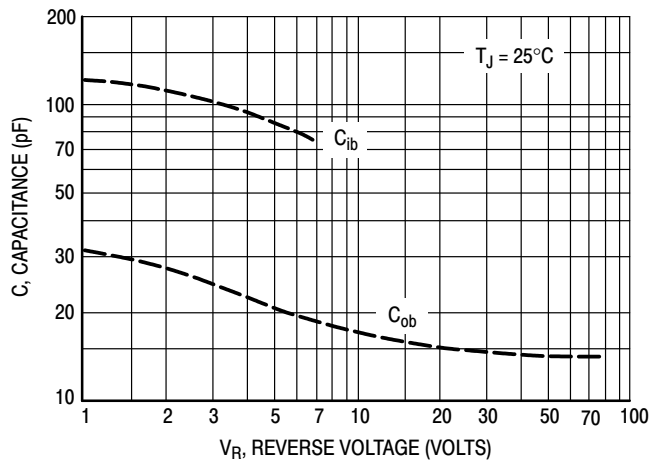


Figure 11. Capacitance

MJD243 (NPN), MJD253 (PNP)

ORDERING INFORMATION

| Device | Package Type | Package | Shipping† |
|---------------|---------------------|---------|---------------------|
| MJD243G | DPAK-3 (Pb-Free) | 369C | 75 Units / Rail |
| MJD243T4G | DPAK-3 (Pb-Free) | 369C | 2,500 / Tape & Reel |
| NJVMJD243T4G* | DPAK-3 (Pb-Free) | 369C | 2,500 / Tape & Reel |
| MJD253-1G | IPAK (Pb-Free) | 369D | 75 Units / Rail |
| MJD253T4G | DPAK-3 (Pb-Free) | 369C | 2,500 / Tape & Reel |
| NJVMJD253T4G* | DPAK-3 (Pb-Free) | 369C | 2,500 / Tape & Reel |

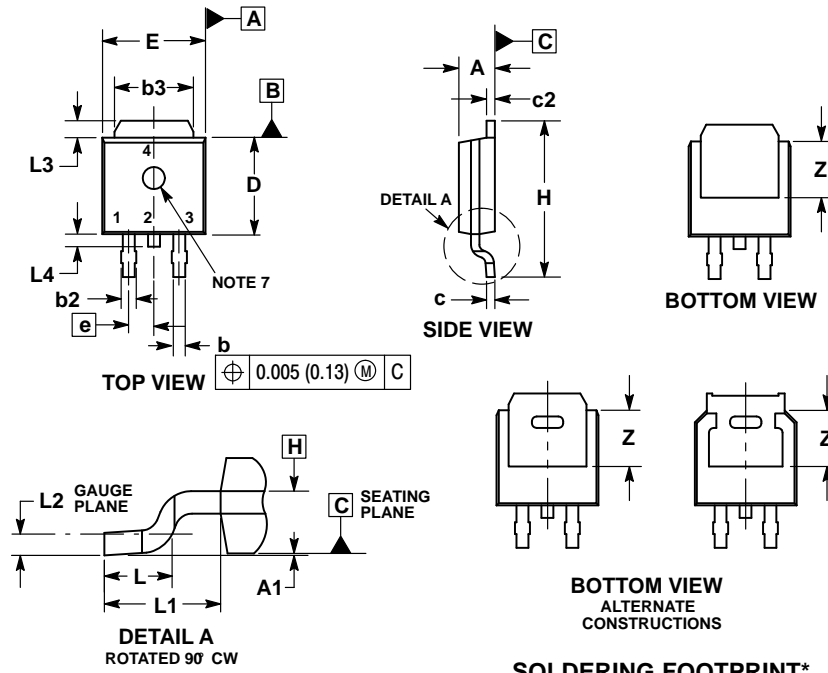
†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

*NJV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable

MJD243 (NPN), MJD253 (PNP)

PACKAGE DIMENSIONS

DPAK (SINGLE GAUGE) CASE 369C ISSUE F

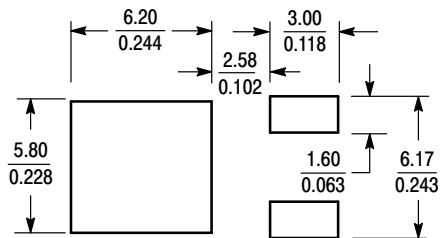


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: INCHES.
3. THERMAL PAD CONTOUR OPTIONAL WITHIN DIMENSIONS b3, L3 and Z.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.006 INCHES PER SIDE.
5. DIMENSIONS D AND E ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY.
6. DATUMS A AND B ARE DETERMINED AT DATUM PLANE H.
7. OPTIONAL MOLD FEATURE.

| DIM | INCHES | | MILLIMETERS | |
|-----|-----------|-------|-------------|-------|
| | MIN | MAX | MIN | MAX |
| A | 0.086 | 0.094 | 2.18 | 2.38 |
| A1 | 0.000 | 0.005 | 0.00 | 0.13 |
| b | 0.025 | 0.035 | 0.63 | 0.89 |
| b2 | 0.028 | 0.045 | 0.72 | 1.14 |
| b3 | 0.180 | 0.215 | 4.57 | 5.46 |
| c | 0.018 | 0.024 | 0.46 | 0.61 |
| c2 | 0.018 | 0.024 | 0.46 | 0.61 |
| D | 0.235 | 0.245 | 5.97 | 6.22 |
| E | 0.250 | 0.265 | 6.35 | 6.73 |
| e | 0.090 BSC | | 2.29 BSC | |
| H | 0.370 | 0.410 | 9.40 | 10.41 |
| L | 0.055 | 0.070 | 1.40 | 1.78 |
| L1 | 0.114 REF | | 2.90 REF | |
| L2 | 0.020 BSC | | 0.51 BSC | |
| L3 | 0.035 | 0.050 | 0.89 | 1.27 |
| L4 | --- | 0.040 | --- | 1.01 |
| Z | 0.155 | --- | 3.93 | --- |

SOLDERING FOOTPRINT*



SCALE 3:1 $\left(\frac{\text{mm}}{\text{inches}}\right)$

STYLE 1:

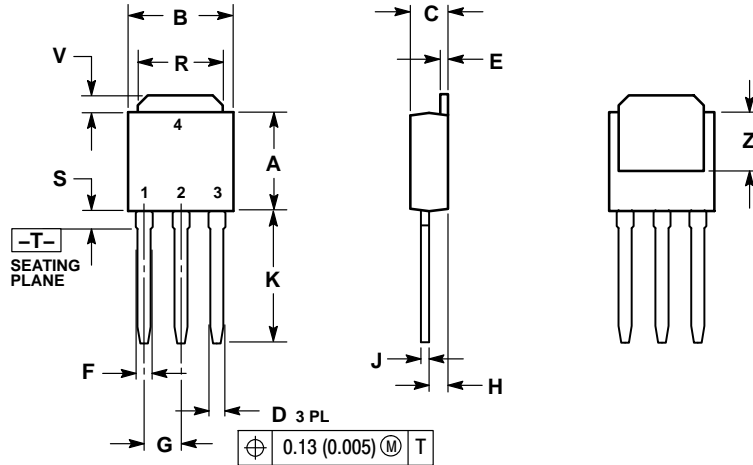
- PIN 1. BASE
2. COLLECTOR
3. EMITTER
4. COLLECTOR

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

MJD243 (NPN), MJD253 (PNP)

PACKAGE DIMENSIONS

IPAK CASE 369D ISSUE C



- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.

| DIM | INCHES | | MILLIMETERS | |
|-----|--------|-------|-------------|------|
| | MIN | MAX | MIN | MAX |
| A | 0.235 | 0.245 | 5.97 | 6.35 |
| B | 0.250 | 0.265 | 6.35 | 6.73 |
| C | 0.086 | 0.094 | 2.19 | 2.38 |
| D | 0.027 | 0.035 | 0.69 | 0.88 |
| E | 0.018 | 0.023 | 0.46 | 0.58 |
| F | 0.037 | 0.045 | 0.94 | 1.14 |
| G | 0.090 | BSC | 2.29 | BSC |
| H | 0.034 | 0.040 | 0.87 | 1.01 |
| J | 0.018 | 0.023 | 0.46 | 0.58 |
| K | 0.350 | 0.380 | 8.89 | 9.65 |
| R | 0.180 | 0.215 | 4.45 | 5.45 |
| S | 0.025 | 0.040 | 0.63 | 1.01 |
| V | 0.035 | 0.050 | 0.89 | 1.27 |
| Z | 0.155 | --- | 3.93 | --- |

- STYLE 1:
 PIN 1. BASE
 2. COLLECTOR
 3. EMITTER
 4. COLLECTOR

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